

GooLED-VOS-7830 Pin Fin LED Heat Sink Φ78mm for Vossloh-Schwabe

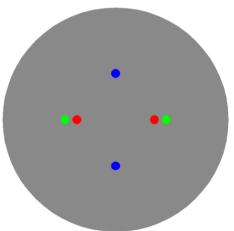
Features VS Benefits

- * The GooLED-VOS-7830 Vossloh-Schwabe Pin Fin LED Heat Sinks are specifically designed for luminaires using the Vossloh-Schwabe LED engines.
- * Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
- * For spotlight and downlight designs from 1,000 to 2,700 lumen.
- * Thermal resistance range Rth 3.03°C/W.
- * Modular design with mounting holes foreseen for direct mounting of Vossloh-Schwabe COB series.
- * Diameter 78.0mm standard height 30.0mm Other heights on request.
- * Forged from highly conductive aluminum.

Zhaga LED engine and radiator assembly is a unified future international standardization

- * Below you find an overview of Vossloh-Schwabe COB's and LED modules which standard fit on the Pin Fin LED Heat Sinks.
- * In this way mechanical after work and related costs can be avoided, and lighting designers can standardize their designs on a limited number of LED Pin Fin LED Heat Sink.





Vossloh-Schwabe LED Modules directly Mounting Options Vossloh-Schwabe LUGA Shop Gen. 5/ Gen.6 COB Series (28.0*28.0):

DMS120***G: DMS120***H; DMS18C***G;

Vossloh-Schwabe LUGA Shop TW COB Series:

With the Zhaga Book 3 holders for the green indicator marks.

BJB holder: 47.319.2030.50; AAG.STUCCHI: 8102-G2

Without the holders for the blue indicator marks.

Vossloh-Schwabe LUGA Shop Gen. 5/ Gen.6 COB Series (19.0*19.0):

DMS126***H;

Vossloh-Schwabe LUGA Shop TW COB Series:

Direct mounting with machine screws M3x6.5mm.





GOOLED

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Mounting Options and Drawings & Dimensions

Example:GooLED-VOS-7830-B-1,2

Example:GooLED-VOS-78 1 - 2 - 3



Anodising Color

B-Black

C-Clear

Z-Custom

Mounting Options - see graphics for details Combinations available

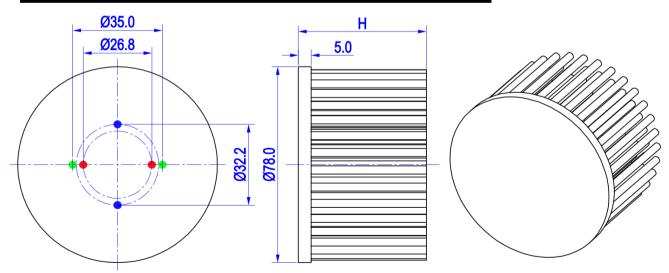
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means option 1 and 2 combined

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

MOUNTING OPTION	Module type	Holder NO.	THREAD	THREAD DEPTH	THREAD HOLE DISTANCE
1	COB series (19.0*19.0)	1	М3	6.5mm	26.8mm/ 2-@180°
2	COB series (28.0*28.0)	/	М3	6.5mm	32.2mm/ 2-@180°
		BJB Holder 47.319.2030.50	МЗ	6.5mm	35.0mm/ 2-@180° (Zhaga book 3)
3		AAG.STUCCHI 8102-G2			
3	COB series (19.0*19.0)	BJB Holder 47.319.2021.50			
		AAG.STUCCHI 8101-G2			





The product deta table

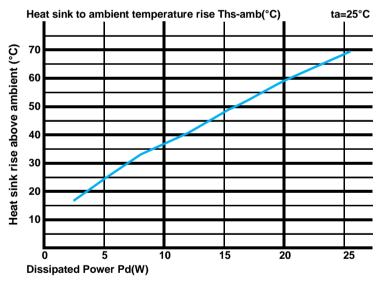


Model No.	GooLED-VOS-7830		
Heatsink Size	Ф78хH30mm		
Heatsink Material	AL1070		
Finish	Black Anodized		
Weight (g)	138.0		
Dissipated power (Ths-amb,50℃)	16.5 (W)		
Cooling surface area (mm²)	46643		
Thermal Resistance (Rhs-amb)	3.03 (°C/W)		

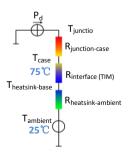
The thermal data table

- * Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.
- *To calculate the dissipated power please use the following formula: $Pd = Pe \times (1-\eta L)$.
 - Pd Dissipated power ; Pe Electrical power ; $\eta L = \text{Light effciency of the LED module};$

	Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)				
			GooLED-VOS-7830					
(W.	(W)	5.0	4.80	24.0				
	Dissipated Power Pd(W)	10.0	3.60	36.0				
		15.0	3.13	47.0				
sipate	20.0	2.95	59.0					
	Dis	25.0	2.72	68.0				



- *The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).
- $\label{thm:mingFa} \mbox{MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.}$
- $Either thermal\ grease, A\ thermal\ pad\ or\ a\ phase\ change\ thermal\ pad\ thickness\ 0.\ I-0.\ I\ 5mm\ is\ recommended.$



- *Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow. Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (Ths Ta)/Pd$
- $\theta\,$ Thermal Resistance [°C/W] ; $\,$ Ths Heatsink temperature ; $\,$ Ta Ambient temperature ;
- *The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is $R_{junction-case}$, the thermal resistance of the TIM outside the package is $R_{interface}$ (TIM) [°C/M], the thermal resistance with the heat sink is $R_{heatsink-ambient}$ [°C/M], and the ambient temperature is $T_{ambient}$ [°C/].
- *Thermal resistances outside the package $R_{interface\,(TIM)}$ and $R_{heatsink-ambient}$ can be integrated into the thermal resistance $R_{case-ambient}$ at this point. Thus, the following formula is also used:

 $T_{junction} = (R_{junction-case} + R_{case-ambient}) \cdot Pd + T_{ambient}$